



PK696 (v1.0) Jan 16, 2015

# 100% Material Declaration Data Sheet for Artix<sup>®</sup>-7 Device FB484 Package

**Average Weight: 2.1679 g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					<b>0.237267</b>	<b>10.945</b>
	Silicon	7440-21-3	100.00		0.237267	
Solder Bump					<b>0.011261</b>	<b>0.519</b>
	Tin	7440-31-5	63.00		0.007094	
	Lead	7439-92-1	37.00		0.004167	
Underfill					<b>0.030000</b>	<b>1.384</b>
	Bisphenol F/ epichlorohydrin copolymer	9003-36-5	20.00		0.006000	
	Phenolic resin	Trade Secret	15.00		0.004500	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.00		0.001500	
	Amine type accelerator	Trade Secret	5.00		0.001500	
	Silicon dioxide	60676-86-0	51.50		0.015450	
	Carbon black	1333-86-4	1.00		0.000300	
	Additives	Trade Secret	2.50		0.000750	
Solder Ball						<b>21.250</b>
	Tin	7440-31-5	63.00		<b>0.460670</b>	
	Lead	7439-92-1	37.00		0.290222	
Substrate					0.170448	<b>65.903</b>
	Copper	7440-50-8	36.83		<b>1.428700</b>	
	Tin	7440-31-5	1.11		0.526149	
	Lead	7439-92-1	0.27		0.015854	
	Silver	7440-22-4	0.02		0.003878	
	BT Core	N/A	48.18		0.000288	
	ABF	N/A	11.12		0.688304	
	Solder Mask	N/A	2.48		0.158840	

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## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
01/16/2015	1.0	Xilinx Initial Release

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